

C0603X120F2TACTU

Aliases (C0603X120F2TAC7867) SMD Comm X8G HT150C Flex, Ceramic, 12 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

		Specifications
	0603	Capacitance
	1.6mm +/-0.17mm	Measurement Condition
	0.8mm +/-0.15mm	Tolerance
	0.8mm +/-0.15mm	Voltage DC
	0.4mm MIN	Dielectric Withstanding Ve
	0.45mm +/-0.15mm	Temperature Range
		Temp. Coefficient
specifications		Capacitance Change with

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Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Specifications	
Capacitance	12 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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Dimensions Chip Size

Packaging S

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